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TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOS III)

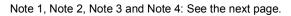
TPC8014

Lithium Ion Battery Applications Portable Equipment Applications Notebook PC Applications

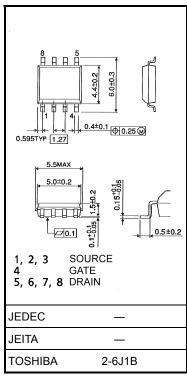
- Small footprint due to small and thin package
- Low drain-source ON resistance: RDS (ON) = 11 m Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 10 \text{ S} (typ.)$
- Low leakage current: $I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 30 \ V)$
- Enhancement mode: $V_{th} = 1.3$ to 2.5 V ($V_{DS} = 10$ V, $I_D = 1$ mA)

Maximum Ratings (Ta = 25°C)

Characte	ristics	Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	30	V	
Drain-gate voltage (R	$d_{GS} = 20 \text{ k}\Omega$)	V _{DGR}	30	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	I _D	11	А	
Drain current	Pulse (Note 1)	I _{DP}	44	~	
Drain power dissipati	. ,	PD	1.9	W	
	(Note 2a)				
Drain power dissipati	on (t = 10 s)	PD	1.0	w	
	(Note 2b)				
Single pulse avalance	ne energy	EAS	157	mJ	
	(Note 3)	LAS	137	115	
Avalanche current		I _{AR}	11	А	
Repetitive avalanche	energy	F	0.19	mJ	
(Note 2a) (Note 4)	E _{AR}	0.19	IIIJ	
Channel temperature	:	T _{ch}	150	°C	
Storage temperature range		T _{stg}	–55 to 150	°C	

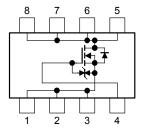


This transistor is an electrostatic-sensitive device. Please handle with caution.



Weight: 0.08 g (typ.)

Circuit Configuration

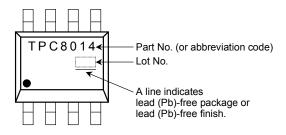


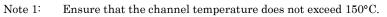
Unit: mm

Thermal Characteristics

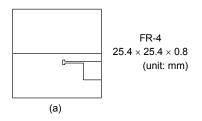
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient $(t=10 \ s) \ (Note \ 2a)$	R _{th (ch-a)}	65.8	°C/W
Thermal resistance, channel to ambient $(t=10 \ s) \mbox{ (Note 2b)} \label{eq:kappa}$	R _{th (ch-a)}	125	°C/W

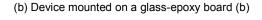
Marking (Note 5)

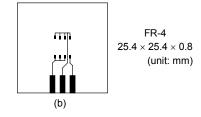




Note 2: (a) Device mounted on a glass-epoxy board (a)







- Note 3: $V_{DD} = 24 V$, $T_{ch} = 25^{\circ}C$ (initial), L = 1.0 mH, $R_G = 25 \Omega$, $I_{AR} = 11 \text{ A}$
- Note 4: Repetitive rating: pulse width limited by max channel temperature
- Note 5: on lower left of the marking indicates Pin 1.



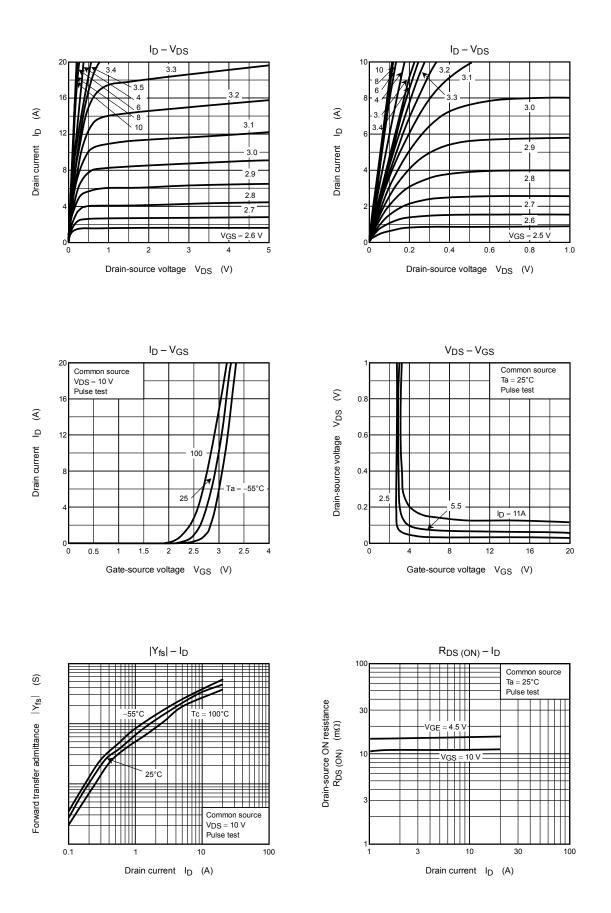
Electrical Characteristics (Ta = 25°C)

Cha	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS}=\pm 16~V,~V_{DS}=0~V$		_	±10	μA
Drain cut-OFF cu	irrent	I _{DSS}	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			10	μA
Drain agurag bra	a cut-OFF current source breakdown voltage threshold voltagesource ON resistance ard transfer admittance capacitance rese transfer capacitance ut capacitance capacitance Fishing time Fall time Turn-OFF time	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	30		_	V
Dialit-Source brea	akuown vollage	V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	15	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	v	
Gate threshold vo	oltage	V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	1.3		- 2.5 15 22 11 14 10 - 1860 - 270 -	
	registeres	Decement	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 5.5 \text{ A}$	_	15	22	
Drain-source ON resistance		RDS (ON)	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 5.5 \text{ A}$	_	11	14	mΩ
Forward transfer	admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 5.5 \text{ A}$	I _D = 5.5 A 5 10			S
Input capacitance	apacitance			_	1860	_	
Reverse transfer	capacitance	C _{rss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	270		pF
Output capacitan	се	C _{oss}		_	320	_	
	Rise time	tr			9	_	
Outitabies times	$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	_					
Switching time	Fall time	t _f	$V_{DD} \simeq 15 V$	_	20	_	- ns
	Turn-OFF time	t _{off}			69	_	
Total gate charge (gate-source plus gate-drain)		Qg			39		nC
Gate-source charge 1		Q _{gs1}	$V_{DD} \simeq 24 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 11 \text{ A}$		4		
Gate-drain ("miller") charge		Q _{gd}		_	9	_	

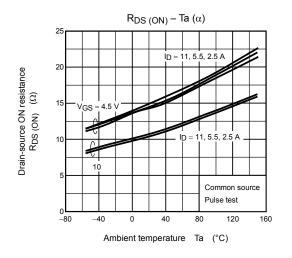
Source-Drain Ratings and Characteristics (Ta = 25°C)

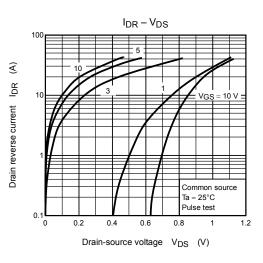
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Drain reverse current	Pulse	(Note 1)	I _{DRP}	—	_		44	А
Forward voltage (diode)			V _{DSF}	$I_{DR} = 11 \text{ A}, V_{GS} = 0 \text{ V}$		_	-1.2	V

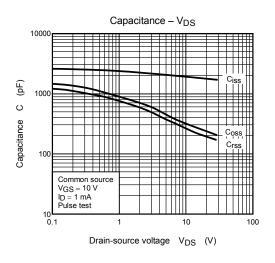
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P_D – Ta

100

Ambient temperature Ta (°C)

_(1).

(2)

1.6

1.2

0.8

0.4

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PD

Drain power dissipation

Device mounted on a glass-epoxy board (a)

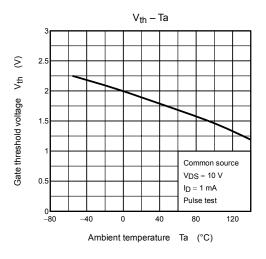
(2) Device mounted on a glass-epoxy board (b) (Note 2b)

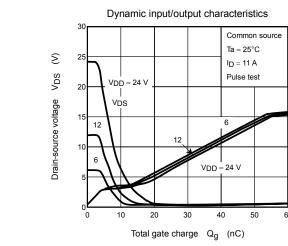
150

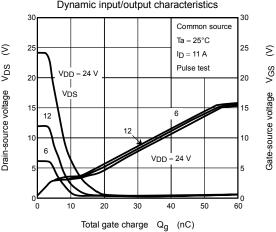
200

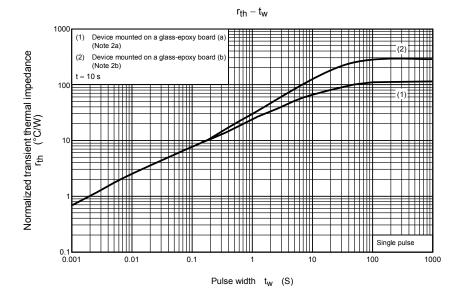
(Note 2a)

= 10 s

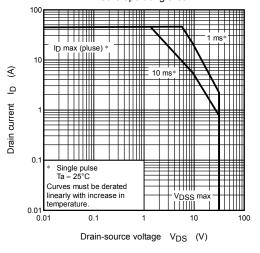








Safe operating area



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